TECHNICAL DATASHEET:
BERGQUIST GAP PAD TGP 7000ULM

PRODUCT DESCRIPTION

A 7.0 W/m·K, extremely soft Gap Pad with exceptional thermal performance at low pressures. BERGQUIST GAP PAD TGP 7000ULM is an extremely soft gap filling material rated at a thermal conductivity of 7.0 W/m·K. It is specially formulated for high-performance applications requiring low assembly stress, and offers exceptional thermal performance at low pressures due to its unique filler package and ultra-low modulus resin formulation. The material is highly conformal to rough or irregular surfaces, allowing excellent wet-out at the interface. Protective liners are supplied on both sides for ease of use.

TYPICAL APPLICATIONS

- Telecommunications (routers, switches, base stations)
- Optical transceivers
- ASICs and DSPs

PRODUCT FEATURES & BENEFITS

- Thermal conductivity: 7.0 W/m·K
- High compliance, low compression stress
- Ultra-low modulus (152 kPa)
- Highly conformal to rough or irregular surfaces
- UL 94 V-0 flammability rating
- Protective liners on both sides

PRODUCT SPECIFICATIONS

Technology	Silicone
Appearance	Gray
Interface Tack	2 sides
Thickness	0.5 to 3.18 mm
Application	Thermal Management / TIM (Thermal Interface Material)
Operating Temperature Range	-60 to 200°C
UL Flammability Rating	UL 94 V-0
Configurations Available	Sheet size 8" x 8"; standard thicknesses 0.02, 0.04, 0.06, 0.08, 0.1, 0.125 in (0.5, 1, 1.5, 2.0, 2.5, 3.18 mm)
Shelf Life (Optimal Storage)	180 days at 25°C (±3), 50% RH (±10)

Specifications are believed to be accurate at the time of publication and are subject to change without notice. It is the responsibility of the end-user to test and determine suitability of this material for a particular application. H-O will provide samples for this purpose at no charge. **REV. 0**

TYPICAL PROPERTIES OF CURED MATERIAL

TECHNICAL DATA	VALUE	UNIT	TEST METHOD / STANDARD
Physical Properties			
Hardness, Shore 000	75	—	ASTM D2240
Inherent Surface Tack	2	sides	—
Density	3.2	g/cc	ASTM D792
Heat Capacity	1.1	J/g·K	ASTM E1269
Young's Modulus	152 (22)	kPa (psi)	—
Shelf Life	180	days	—
Electrical Properties			
Dielectric Constant @ 1,000 Hz	8.7	—	ASTM D150
Dielectric Breakdown Voltage (40 mil sample)	>5,000	VAC	ASTM D149
Volume Resistivity	1.2×10^{11}	ohm·meter	ASTM D257
Thermal Properties			
Thermal Conductivity	7.0	W/(m·K)	ASTM D5470

STORAGE

Store product in the unopened container in a dry location. Optimal storage: 25°C (±3), 50% RH (±10) for a 180-day shelf life. Material removed from containers may be contaminated during use; do not return product to the original container.

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